



景碩科技股份有限公司
Kinsus Interconnect Technology Co.

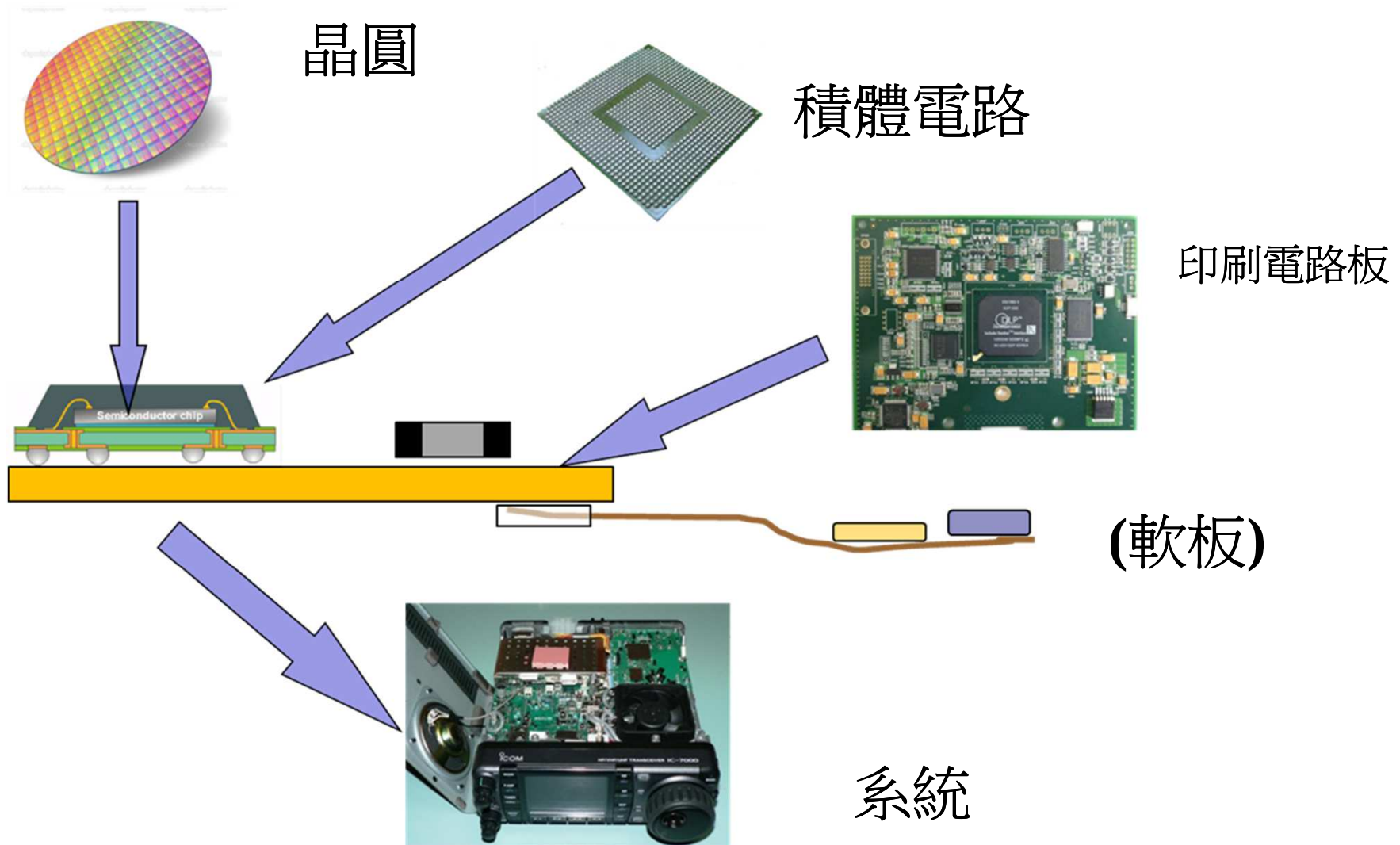
2016 Apr



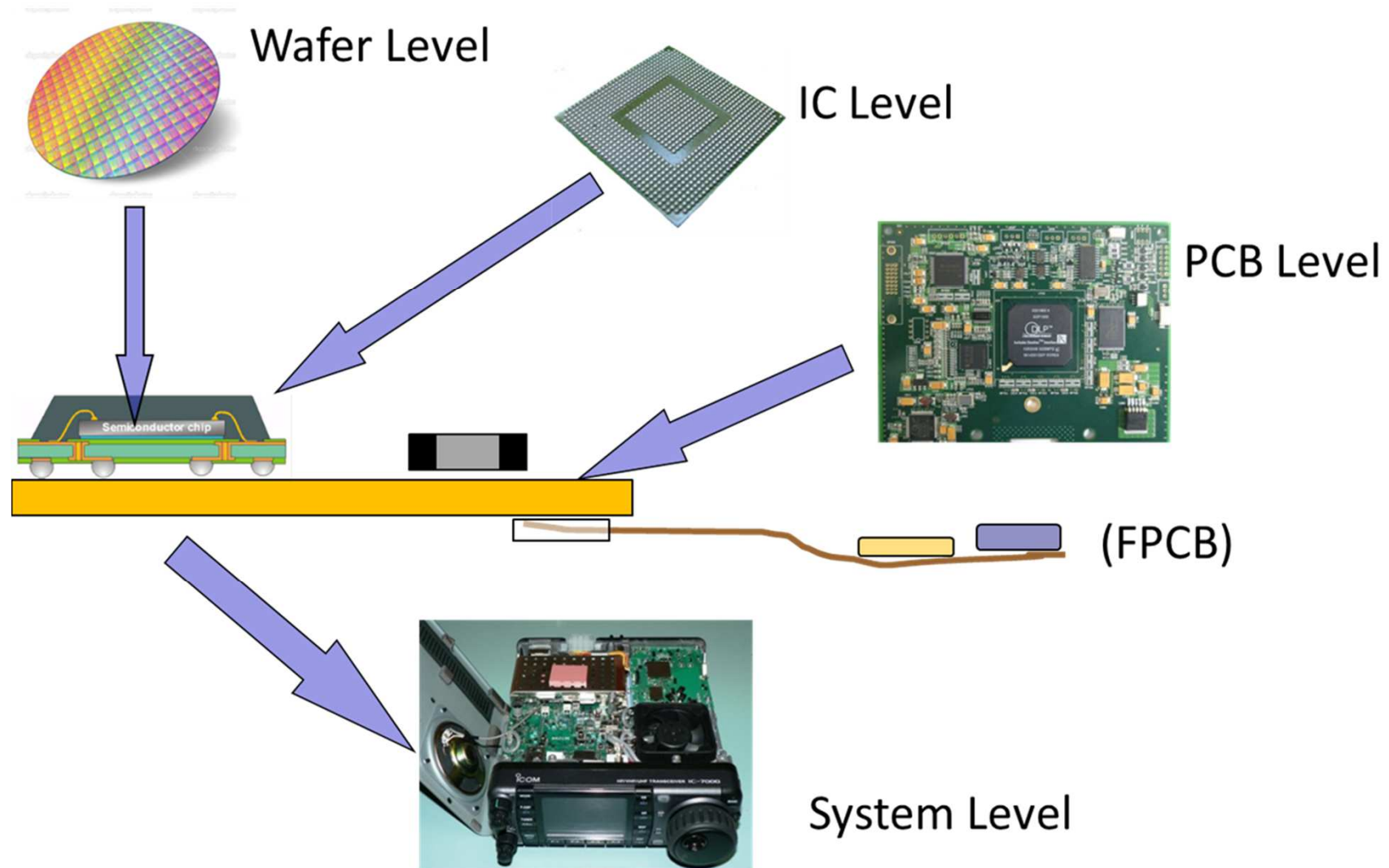
IC 封裝技術

IC Packaging Technology

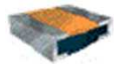
電子產品構裝的各個層次



Levels of Assembly in Electronic Devices



各種形式的 IC 封裝



Chips



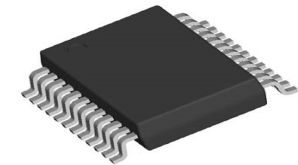
SOT/SOD



DPAK



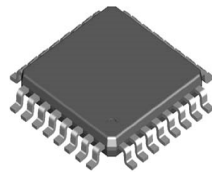
SOJ



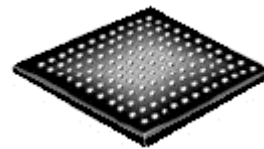
SOIC/SSOP/
OSOP/TSSOP/
MSOP/HSOP



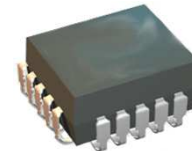
TSOP



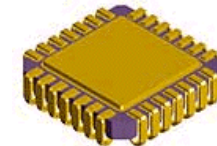
OFP/TOFP
/LOFP



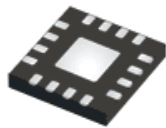
BGA/Flip-Chip
/WLP



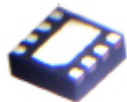
PLCC



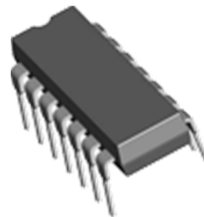
CLCC



QFN



DFN



DIP



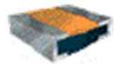
Axial



Radial

Through-hole

Different types of IC packaging



Chips



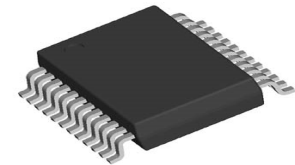
SOT/SOD



DPAK



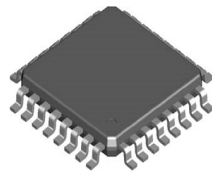
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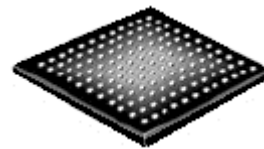
SOIC/SSOP/
OSOP/TSSOP/
MSOP/HSOP



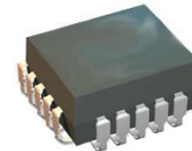
TSOP



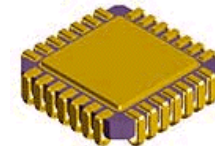
OFP/TOFP
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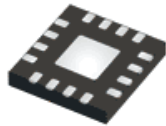
BGA/Flip-Chip
/WLP



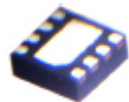
PLCC



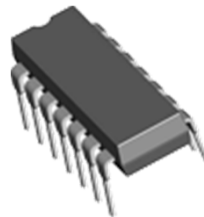
CLCC



QFN



DFN



DIP



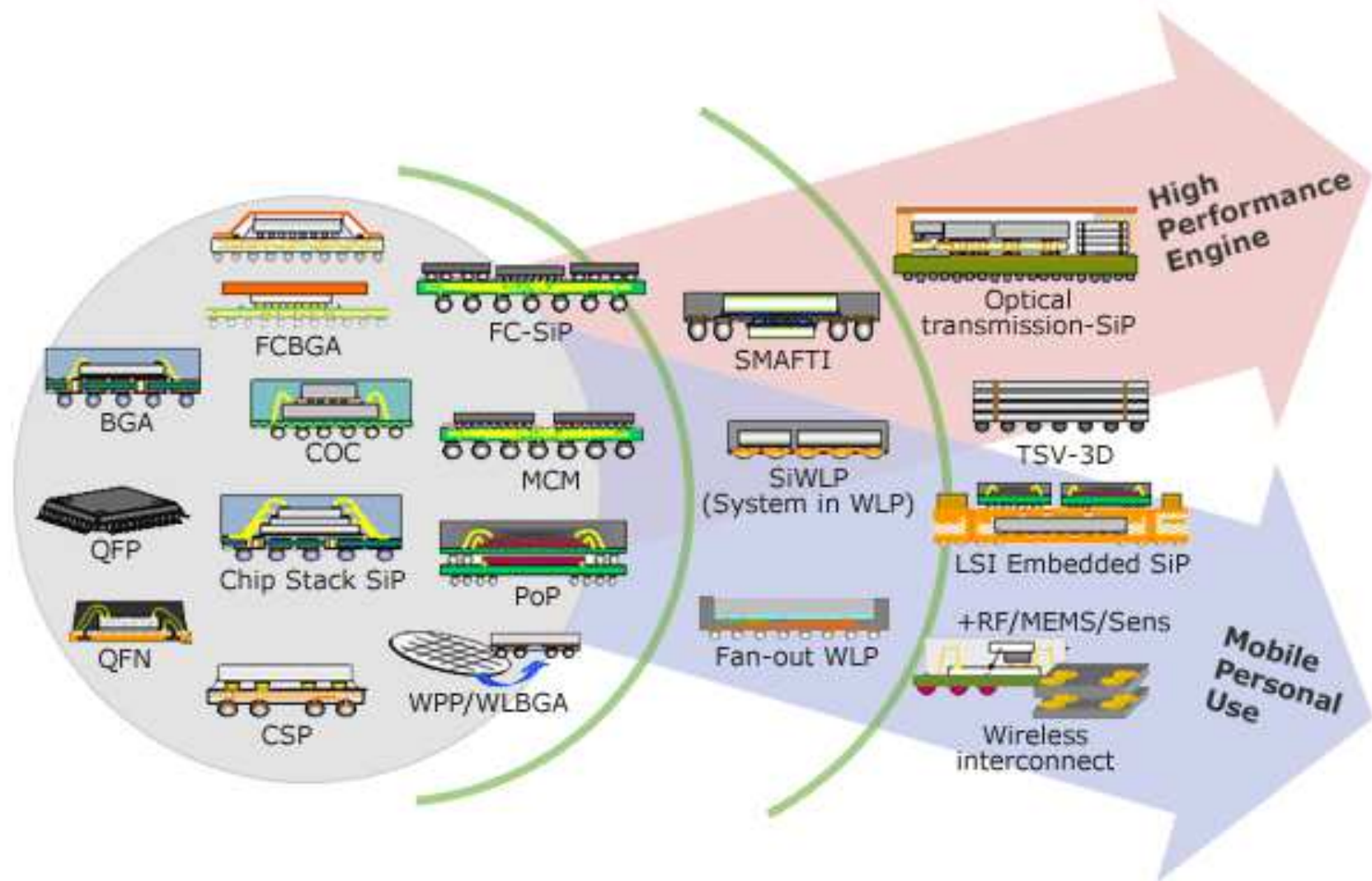
Axial



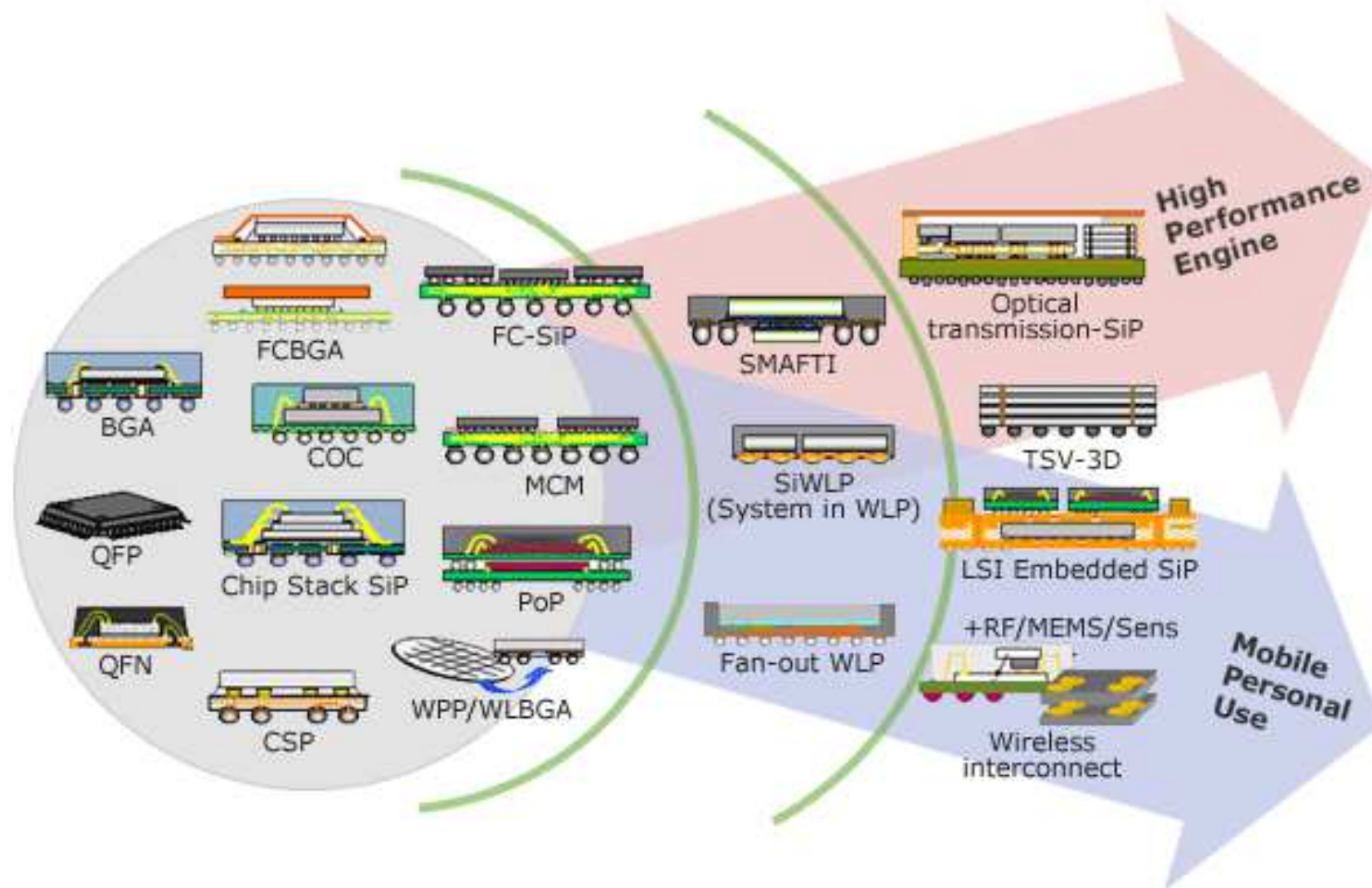
Radial

Through-hole

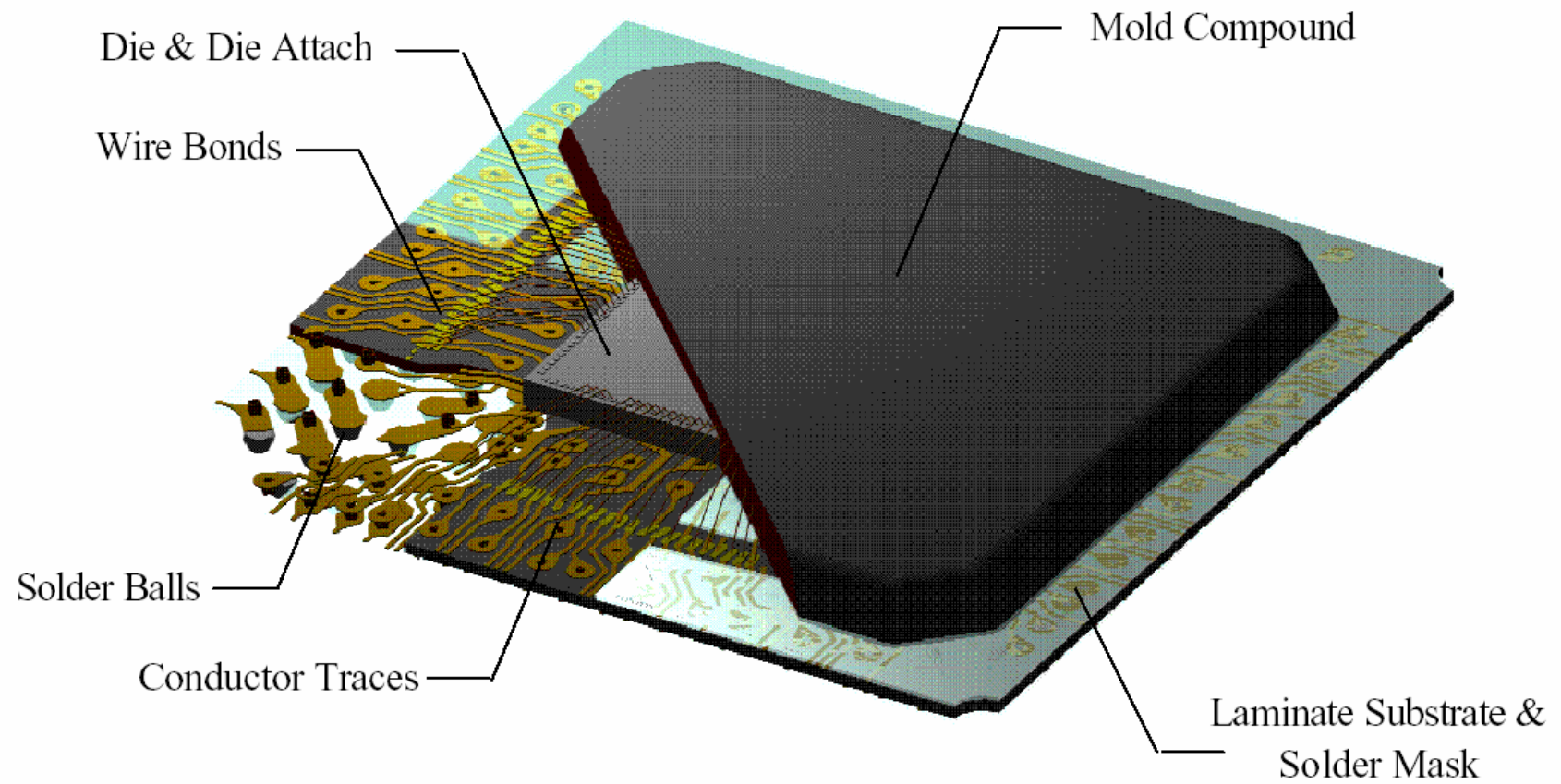
封裝技術走向



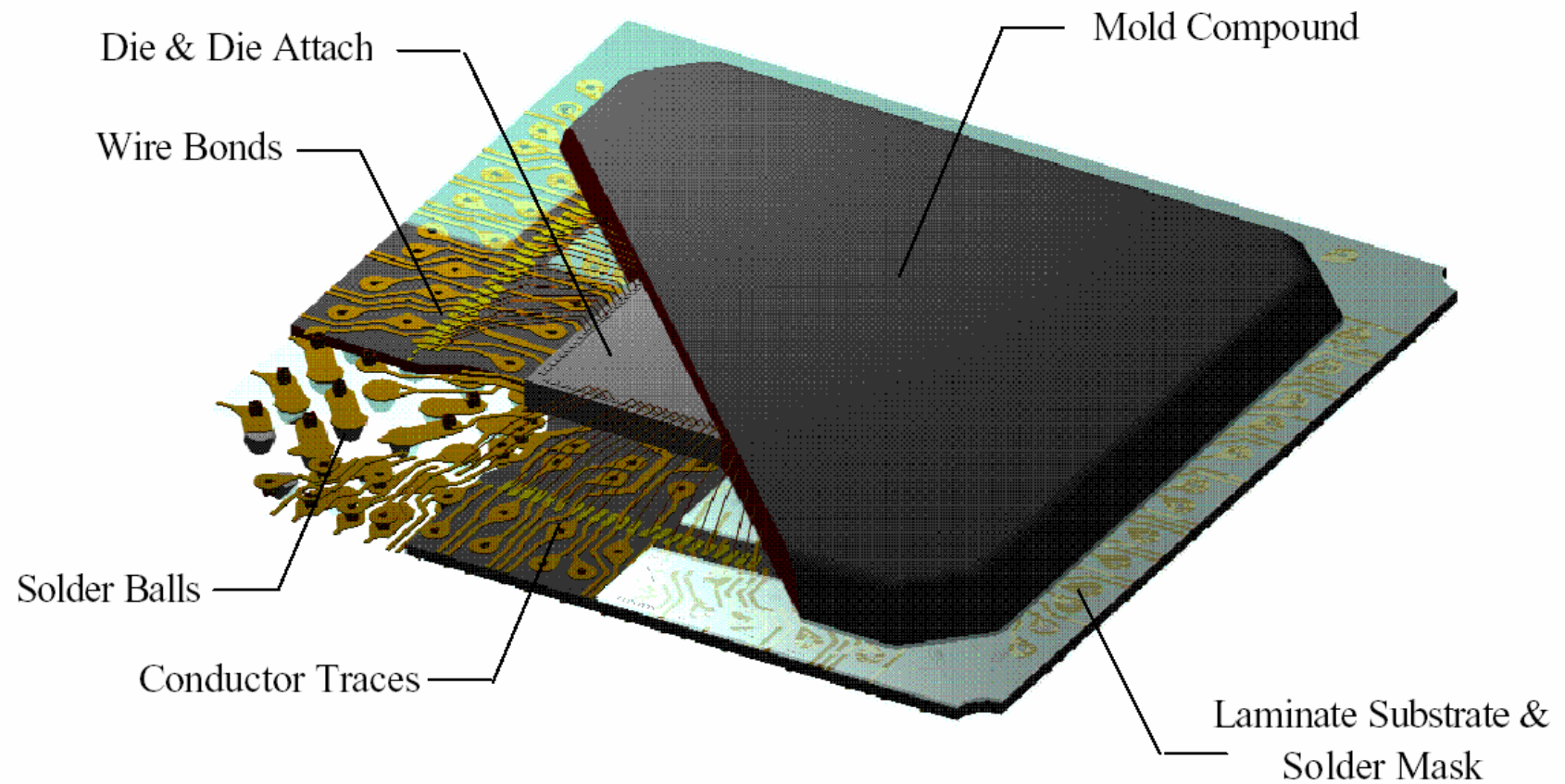
Packaging Technology Roadmap



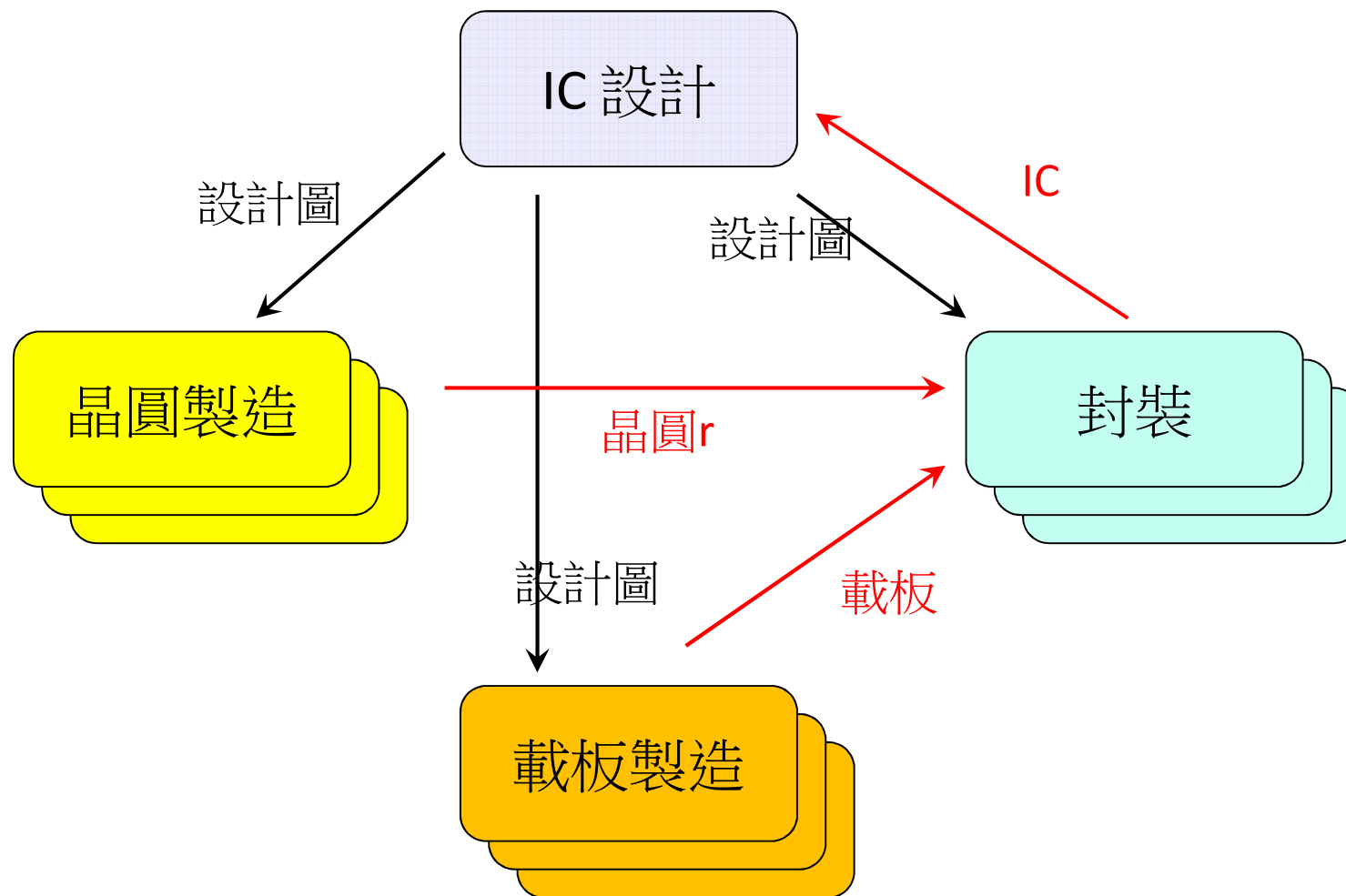
IC 結構



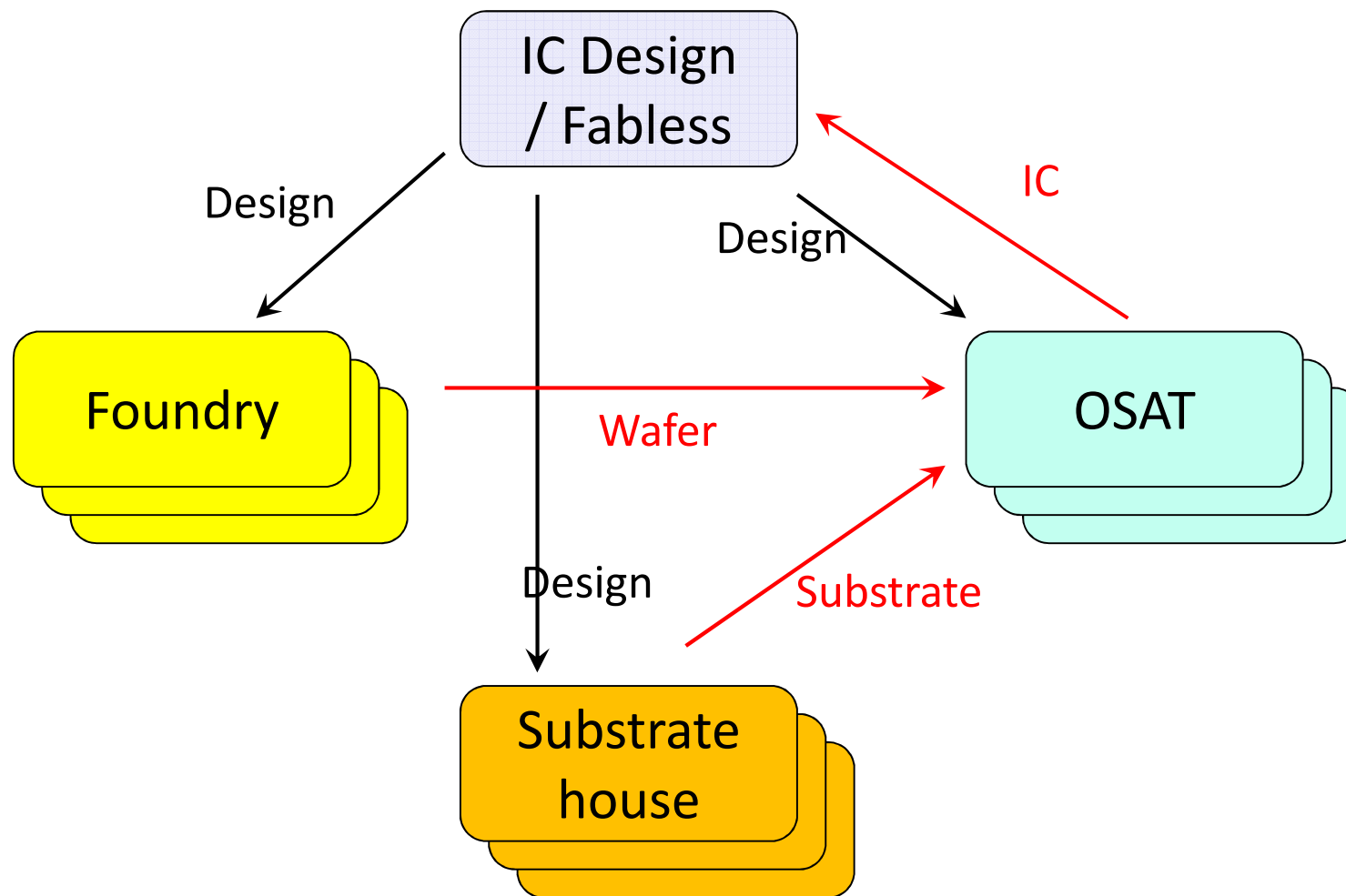
What Substrate Makers do?



IC 半導體上下游供應鏈關係



IC Manufacturing Supply Chain





About Kinsus

基本資料



- 成立 September 2000
上市 November 2004
- 登記資本額 新台幣 44.6 億
- 員工數：3,600 (2016 三月)
- 廠區：
 - 總部
 - 石磊 / 新屋區
 - 硬質載板事業部
 - 一廠, 二廠
 - 五廠
 - 軟質載板事業部
 - 六廠
 - 美國子公司
 - Santa Clara / California
 - 中國子公司
 - 蘇州

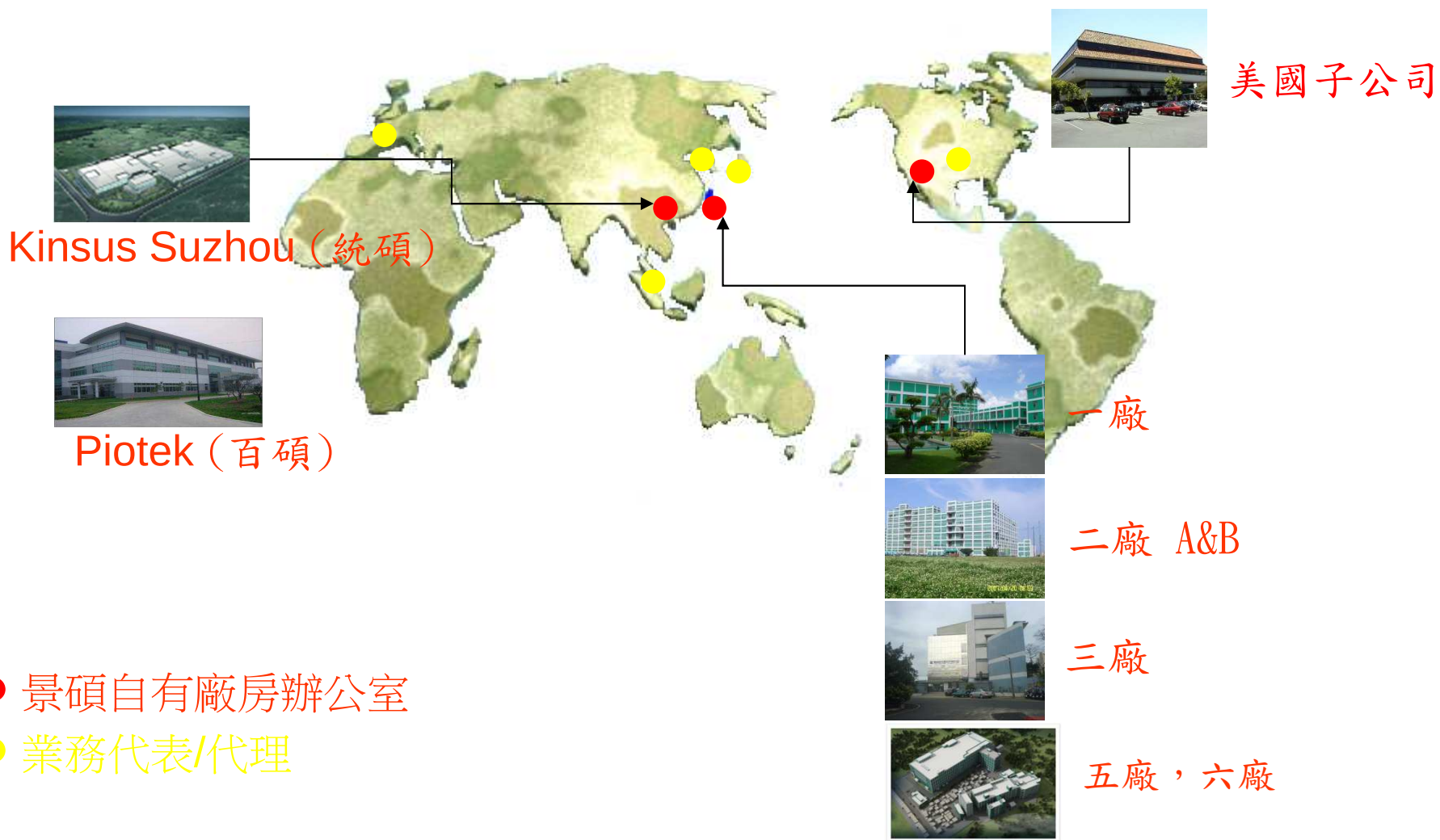
Basic Information



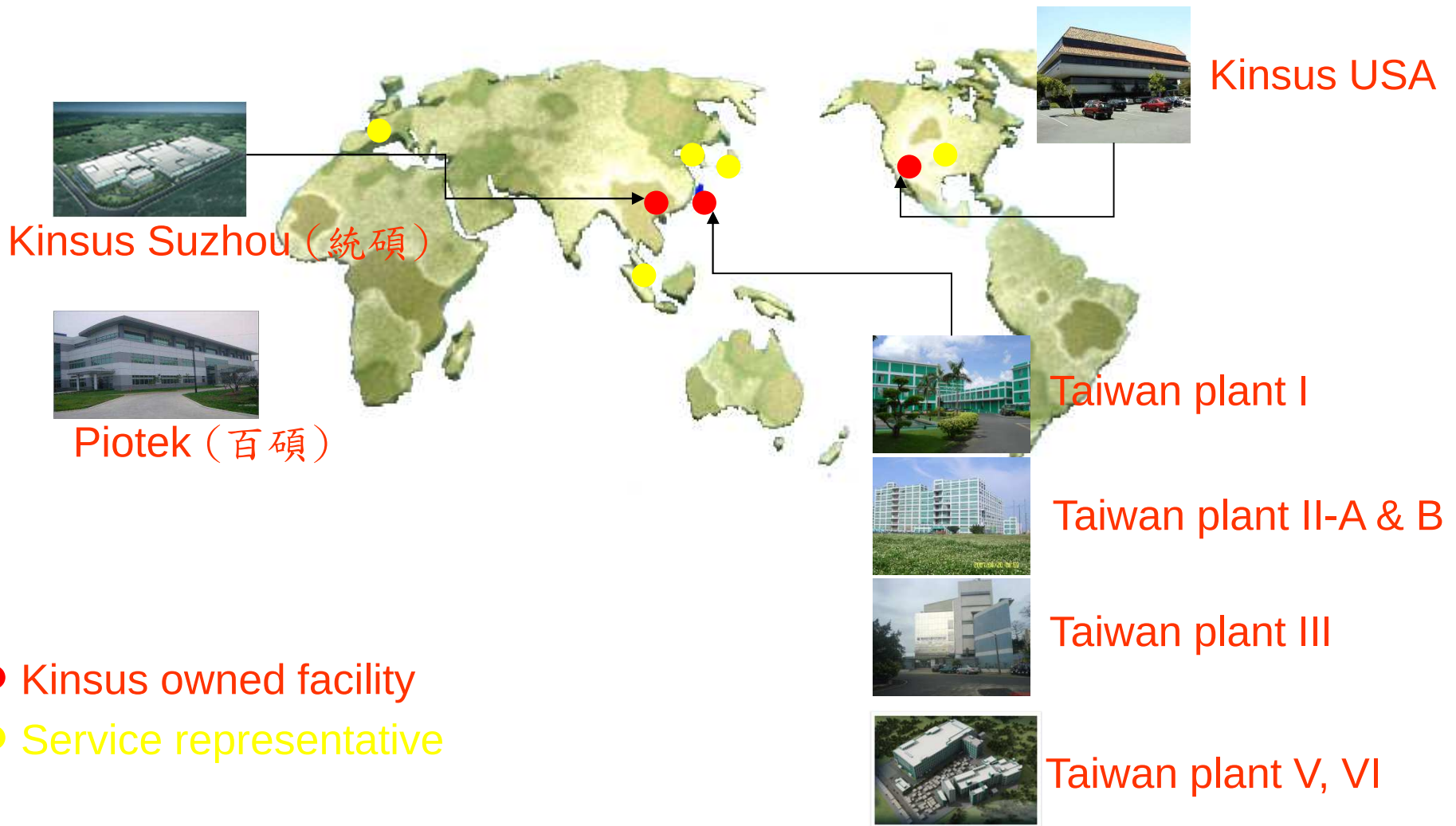
- Established in September 2000
IPO in November 2004
- Capital : US\$ 154 Million (NT\$ 4.46 Billion)
- Headcounts : 3,600 as of March 2016
- Campus :

Headquarters	- Shih Lei / Sin Wu
Rigid Substrates BU	- Plant I, Plant II
	- Plant V
Flexible Substrate BU	- Plant VI
Kinsus USA	- Santa Clara / California
Kinsus China	- Suzhou

位置



Locations



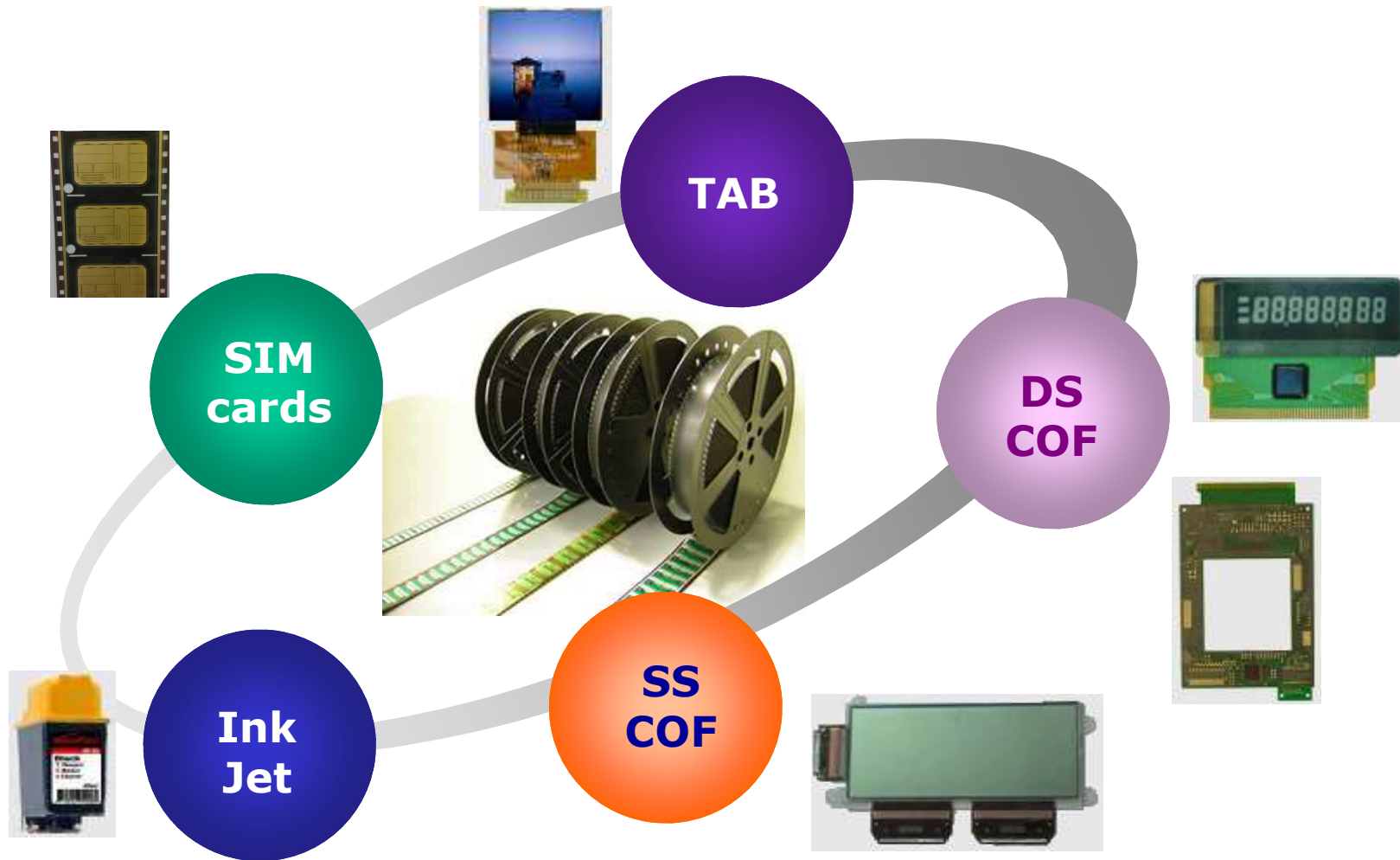
硬質載板產品



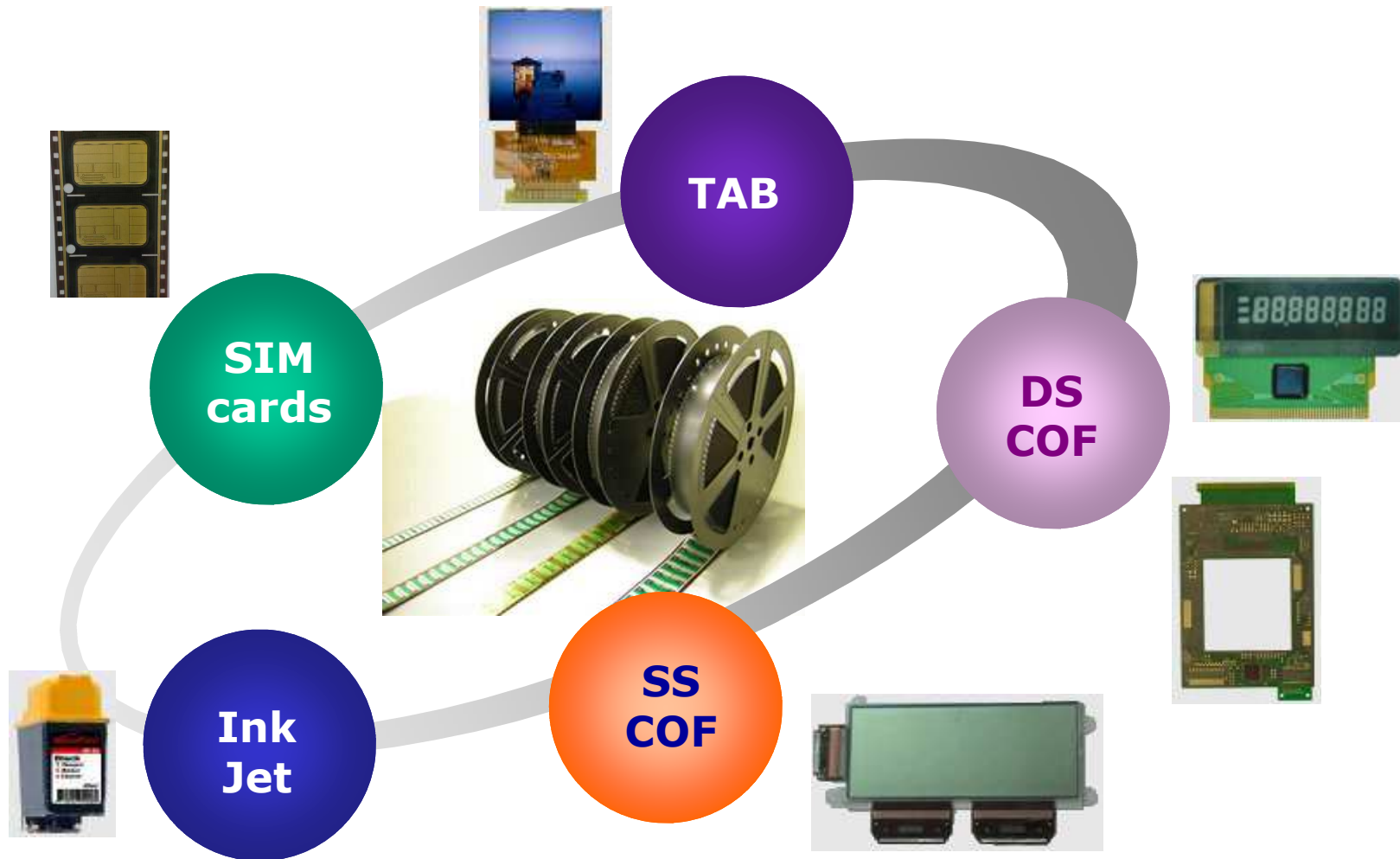
Rigid Substrate Products



軟質載板產品



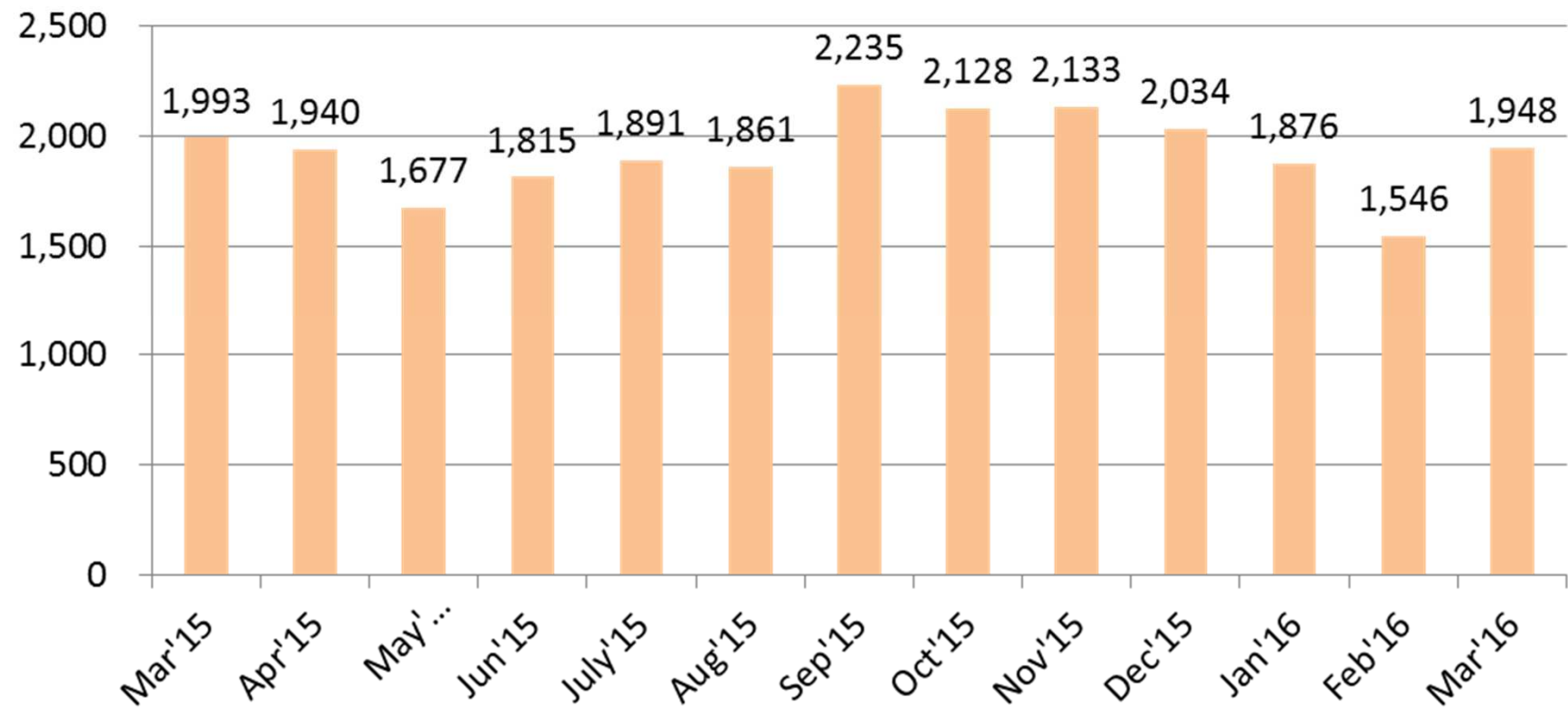
Flexible Substrate Products



每月營業額



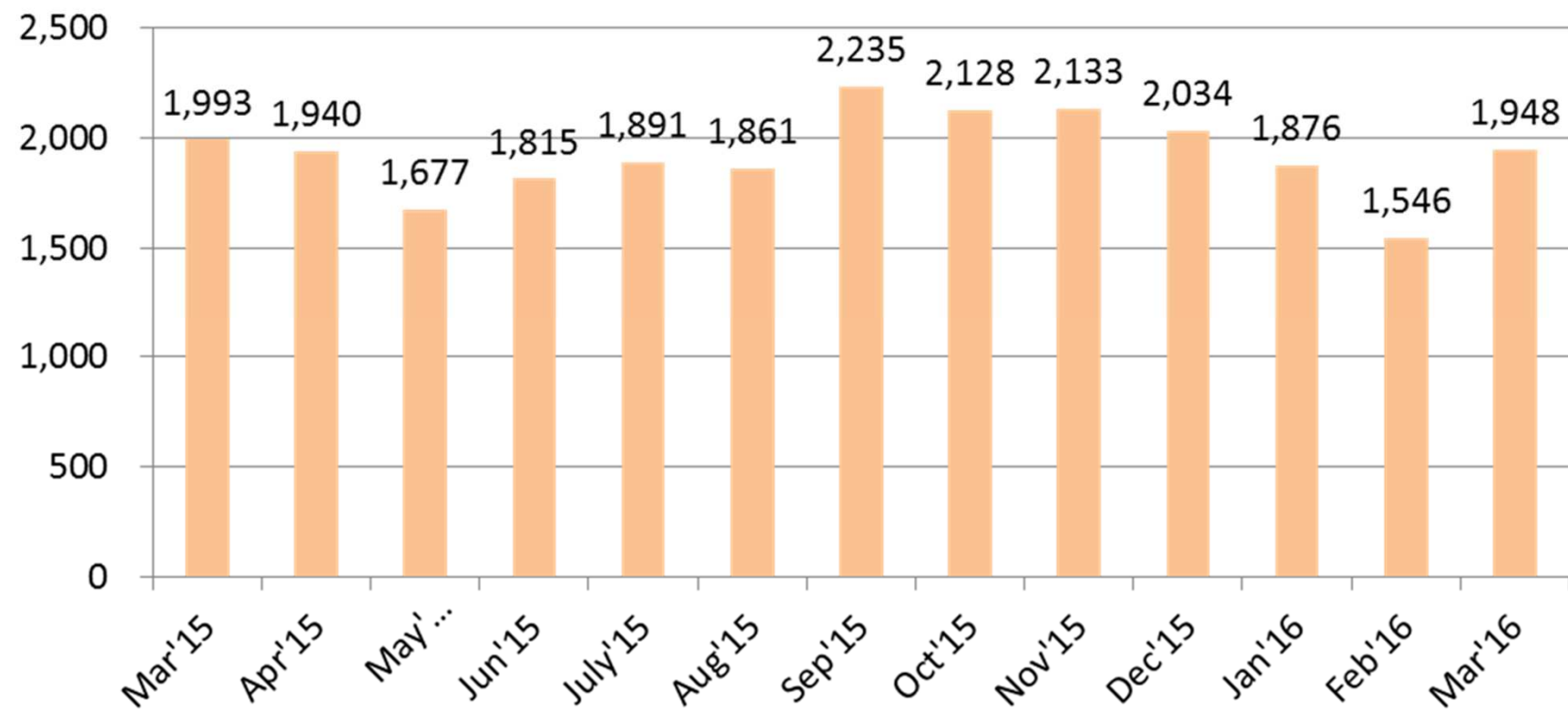
單位：新台幣百萬元



Monthly Revenue



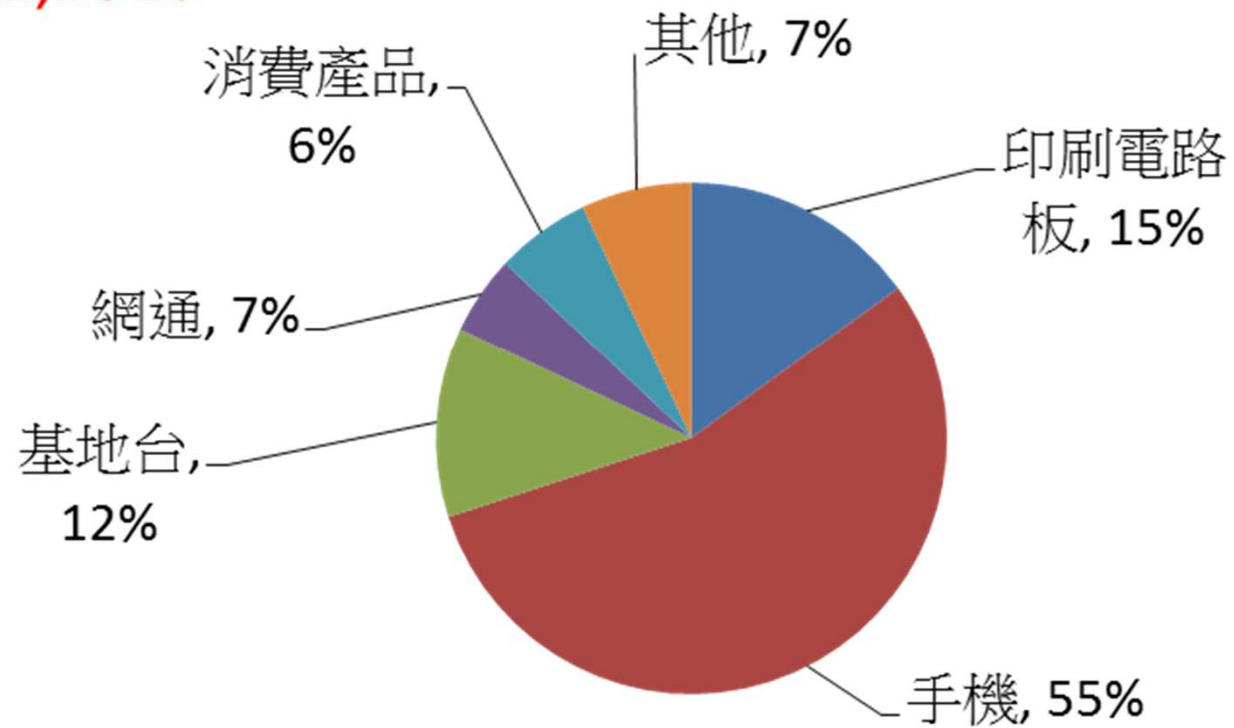
Unit : Million NT\$



營業額分佈



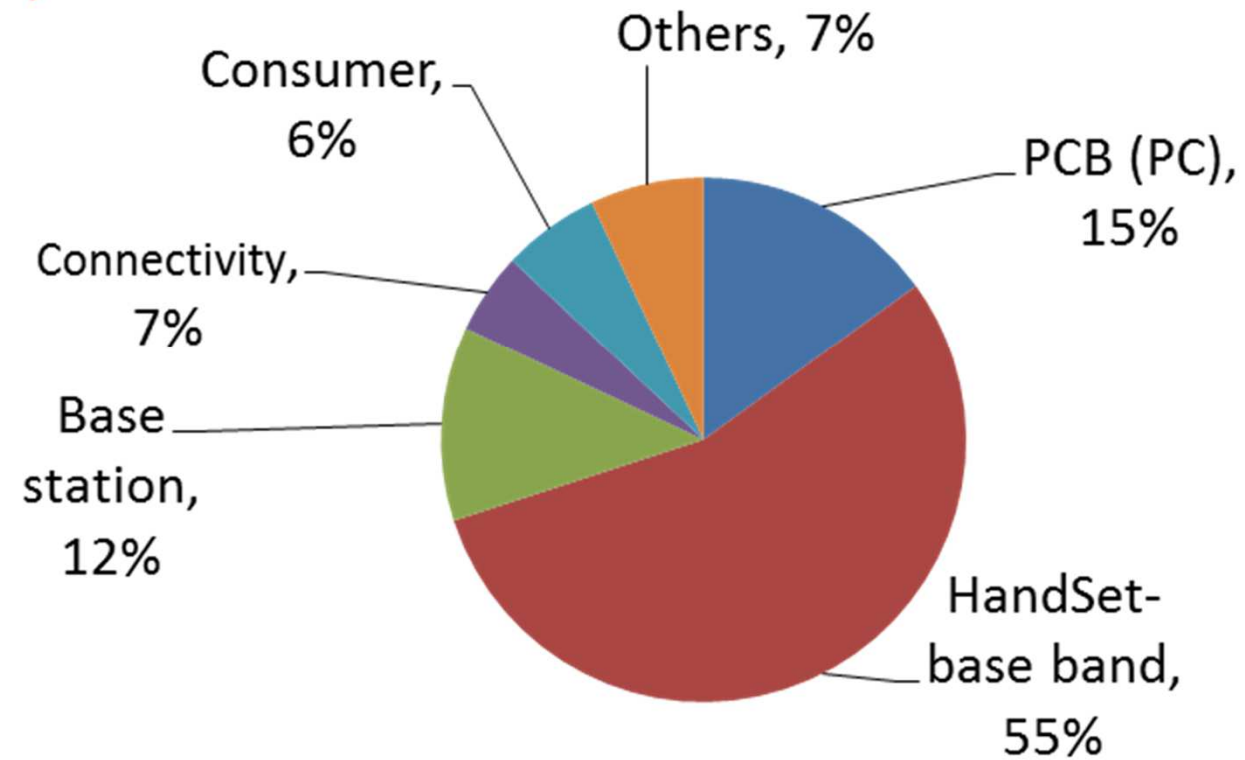
Q1, 2016



Revenue - Application



Q1,2016





Thank You!